

Amendments to the Claims:

Claim 1 (currently amended): A substrate carrier for securing a plurality of semiconductor substrates, comprising:

a ~~e~~assette carrier having,

~~an upper substrate entrance;~~

~~a lower substrate support opening;~~

~~a first end partition disposed opposite a second end partition;~~

axially opposed end partitions and laterally opposed arcuate side panels which are

connected with said end partitions to form a four-sided box structure;

spacing of said arcuate side panels by said end partitions to form a substrate entrance

on top of said carrier, and a narrowed substrate support opening on the bottom side;

~~a first side panel disposed opposite a second side panel, said arcuate side panels having~~

~~an inner surface thereof, with an aligned train of paired~~ substrate support channels for

holding substrates in spaced parallel relation, said channels are formed having two

side surfaces and a bottom surface, said substrate support channels having a curbing

member formed on one side surface of each channel, said curbing member having

[with] a lead-in profile that is sloped and truncated ~~profile, is disposed on an upper~~

~~side of each channel, said curbing member enabl[es]ing~~ a circular substrate to slide

into a substrate support channel [by] past said sloped profile curbing member past a

~~necked portion of opposing channels, therein there-in-after~~ securing said substrate

between the channel support surface and ~~under~~ said curbing member.

Claim 2 (canceled)

Claim 3 (canceled)

Claim 4 (canceled)

Claim 5 (canceled)

Claim 6 (currently amended): The substrate carrier according to claim 1 wherein said substrate support channels are configured to ~~hold~~ secure substrates in a vertical or horizontal orientation.

Claim 7 (currently amended): The substrate carrier according to claim 1 wherein said ~~parallel and perpendicular~~ surfaces of said substrate support channels provide stress free containment of a fragile substrate by providing ~~freedom of~~ lateral movement within the ~~cassette~~ channels while said curbing member prevents ~~ing~~ said substrate from jutting ~~forward past~~ beyond said substrate entrance.

Claim 8 (currently amended): The substrate carrier according to claim 7 wherein said substrate support channels having a “U” shape intended to prevent wedging of said substrate’s ~~highly-stressed~~ brittle edges ~~therefore, thereby~~ reducing chipping ~~and breaking~~ ~~of said highly-stressed~~ of said brittle edges.

Claim 9 (currently amended): The substrate carrier according to claim 1 wherein said ~~bottom of said~~ sloped and truncated profile of said curbing member ~~is shaped to prevent~~ said substrates ~~does not~~ from jutting ~~out beyond the top edge of said cassette~~ said curbing member.

Claim 10 (currently amended): The substrate carrier according to claim 1 wherein [a] the bottom edge of said sloped profile is ~~determined~~ formed to ~~permit~~ give the substrate freedom to move laterally ~~to the limit provided by an offset dimension which is the difference of the lateral offset and the substrate diameter~~

Claim 11 (cancelled)

Claim 12 (cancelled)

Claim 13 (cancelled)

Claim 14 (cancelled)

Claim 15 (cancelled)

Claim 16 (cancelled)

Claim 17 (cancelled)

Claim 18 (cancelled)

Claim 19 (cancelled)

Claim 20 (cancelled)

Claim 21 (currently amended): A method for protecting a plurality of semiconductor substrates in a substrate carrier, comprising the steps of:

providing a ~~easette~~ carrier having,

~~an upper substrate entrance;~~

~~a lower substrate support opening;~~

axially opposed end partitions and laterally opposed arcuate shaped side panels which are connected to said end partitions to form a four-sided box structure;

spacing of said arcuate shaped side panels by said end partitions to form a substrate entrance on top of said carrier, and a narrowed substrate support opening on the bottom side;

~~a first side panel~~ said side panels having an inner surface thereof, with a train of parallel substrate support channels for supporting substrates in spaced parallel relation, said ~~substrate support channels~~ are formed having [a] two side surfaces and a bottom surface. a left side surface and a right side surface. said left and right side

surfaces are perpendicular to said bottom surface;
a second side panel opposite said first side panel having, on an inner surface, a
matching train of parallel substrate support channels;
said substrate support channels having a curbing member disposed on a left one side
surface in of each [of] said substrate support channel[s], including, said curbing
member, a top end having a sloped and truncated profile facing said entrance of said
cassette and a bottom end having a flat bottom, said top end enabl[es]ing a circular
substrate to easily slide into a substrate support channel, [by a} past said sloped
curbing member profile a necked portion of said substrate support channel, therein
there-in-after retaining and securing said substrate between said substrate support
surface and under said curbing member.

Claim 22 (previously presented): A method according to claim 21 wherein said upper
entrance and said lower substrate support opening providing liquid chemical access to all
surfaces of contained substrates.

Claim 23 (previously presented): A method according to claim 21 wherein said substrate
support channel surfaces are planar thereby permitting unrestrained freedom of the
substrates during wet processes and during handling.

Claim 24 (currently amended): A method according to claim 21 wherein said shape of
said curbing member in operation with said substrate support channel, restricts said
substrate from jutting towards said cassette carrier entrance during handling.

Claim 25 (previously presented): A method according to claim 21 wherein all the
substrate support channels are defined formed to contain a circular disk by a substrate's of
a given diameter, said substrate support channels are equally spaced from immediately

~~adjacent substrates~~ one another.

Claim 26 (currently amended): A method according to claim 21 wherein said substrate support channels are configured to hold substrate[']s in a vertical orientation.

Claim 27 (currently amended): A method according to claim 21 wherein said ~~parallel and perpendicular~~ surfaces of said substrate support channels provide stress free containment of a fragile substrate by providing ~~freedom of lateral~~ movement within the ~~cassette channels~~ while ~~preventing said curbing member secures said~~ substrate from ~~jutting forward past said curbing member~~ within said substrate support channel.

Claim 28 (currently amended): A method according to claim 27 wherein said substrate support channels having a "U" shape to prevent wedging of said substrate's ~~highly stressed brittle~~ edges. thereby resulting in reducing perimeter substrate damage chipping.

Claim 29 (currently amended): A method according to claim 21 wherein said ~~stepped bottom of sloped and truncated profile of~~ said curbing member is ~~placed so that said wafer substrate does not jut out beyond the top edge of said cassette prevents substrates from jutting beyond said curbing member~~.

Claim 30 (currently amended): A method according to claim 21 wherein [an] the bottom edge of said sloped profile of said curbing member is determined formed to allocate give the wafer a substrate with known physical attributes, freedom to move laterally ~~to the limit provided by an offset dimension which is the difference of the lateral offset and the substrate's diameter~~.